# **ON Semiconductor**

# Is Now



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# $\frac{\text{MOSFET}}{\text{N-Channel, SUPERFET}^{\mathbb{R}}} = \frac{\text{N-Channel, SUPERFET}^{\mathbb{R}}}{\text{FRFET}^{\mathbb{R}}}$ $650 \text{ V, } 30 \text{ A, } 110 \text{ m}\Omega$

# **Product Preview**

# **NVHL110N65S3HF**

# **Description**

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for the various power system for miniaturization and higher efficiency.

SUPERFET III HF version provides fast recovery for improved efficiency in high speed switching applications.

### **Features**

- Typ.  $R_{DS(on)} = 89 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. Q<sub>g</sub> = 58 nC)
- Low Effective Output Capacitance (Typ. Coss(eff.) = 510 pF)
- 100% Avalanche Tested
- NVHL Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

# **Applications**

- Automotive On Board Charger HEV-EV
- Automotive DC/DC Converter for HEV-EV

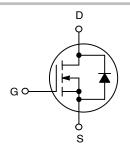
This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.



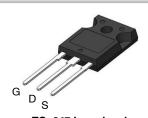
# ON Semiconductor®

### www.onsemi.com

V <sub>DSS</sub>	R <sub>DS(on)</sub> MAX	I <sub>D</sub> MAX
650 V	110 mΩ @ 10 V	30 A

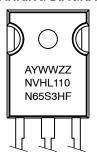


**N-Channel MOSFET** 



TO-247 Long Leads CASE 340CX

### **MARKING DIAGRAM**



A = Assembly Plant Code
YWW = Data Code (Year & Week)
ZZ = Assembly Lot Code
NVHL110N65S3HF = Specific Device Code

# **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

# ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise specified)

Symbol	Parameter	Value	Unit	
V <sub>DSS</sub>	Drain to Source Voltage		650	V
V <sub>GSS</sub>	Gate to Source Voltage	DC	±30	V
		AC (f > 1 Hz)	±30	V
I <sub>D</sub>	Drain Current	Continuous (T <sub>C</sub> = 25°C)	30	Α
		Continuous (T <sub>C</sub> = 100°C)	19.5	
I <sub>DM</sub>	Drain Current	Pulsed (Note 1)	69	Α
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		380	mJ
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		2.4	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		50	
P <sub>D</sub>	Power Dissipation	(T <sub>C</sub> = 25°C)	240	W
		Derate Above 25°C	1.92	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s		300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse-width limited by maximum junction temperature.

2.  $I_{AS} = 3.5 \text{ A}$ ,  $R_{G} = 25 \Omega$ , starting  $T_{J} = 25^{\circ}C$ .

3.  $I_{SD} \le 15 \text{ A}$ ,  $di/dt \le 200 \text{ A}/\mu\text{s}$ ,  $V_{DD} \le 400 \text{ V}$ , starting  $T_{J} = 25^{\circ}C$ .

# THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max.	0.52	°C/W
$R_{ heta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

# PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
NVHL110N65S3HF	NVHL110N65S3HF	TO-247	Tube	N/A	N/A	30 Units

# **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS			•		
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA, T <sub>J</sub> = 25°C	650	_	-	V
		V <sub>GS</sub> = 0 V, I <sub>D</sub> = 10 mA, T <sub>J</sub> = 150°C	700	_	-	V
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 20 mA, Referenced to 25°C	-	0.61	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 650 V, V <sub>GS</sub> = 0 V	_	_	10	μΑ
		V <sub>DS</sub> = 520 V, T <sub>C</sub> = 125°C	_	9	-	
I <sub>GSS</sub>	Gate to Body Leakage Current	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V	_	_	±100	nA
ON CHARACTE	ERISTICS					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}$ , $I_D = 0.74$ mA	3.0	-	5.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A	_	89	110	mΩ
9FS	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 15 A	_	16	-	S
DYNAMIC CHA	RACTERISTICS					
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 400 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	2753	_	pF
C <sub>oss</sub>	Output Capacitance		-	52	-	pF
C <sub>oss(eff.)</sub>	Effective Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V	_	510	-	pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V	_	94	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10 V	V <sub>DS</sub> = 400 V, I <sub>D</sub> = 15 A, V <sub>GS</sub> = 10 V	_	58	-	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	(Note 4)	_	18	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		_	23	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	_	1.6	-	Ω
WITCHING CH	IARACTERISTICS					
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 15 A,	-	27.1	-	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, R_g = 4.7 \Omega$ (Note 4)	_	16.9	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		_	66	-	ns
t <sub>f</sub>	Turn-Off Fall Time		_	2.9	-	ns
SOURCE-DRAI	N DIODE CHARACTERISTICS					
I <sub>S</sub>	Maximum Continuous Source to Drain Diode Forward Current		_	_	30	Α
I <sub>SM</sub>	Maximum Pulsed Source to Drain Diode Forward Current		-	_	69	Α
$V_{SD}$	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 15 A	-	-	1.3	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 15 A,	_	90	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dl <sub>F</sub> /dt = 100 A/μs	-	128	-	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

# TYPICAL CHARACTERISTICS

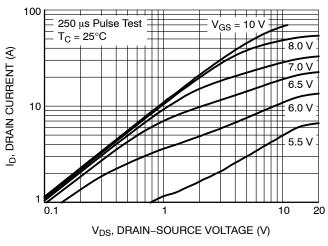


Figure 1. On–Region Characteristics 25°C

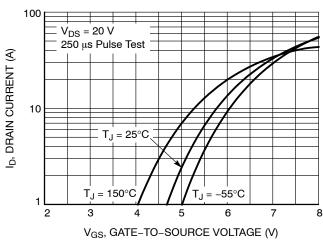


Figure 3. Transfer Characteristics

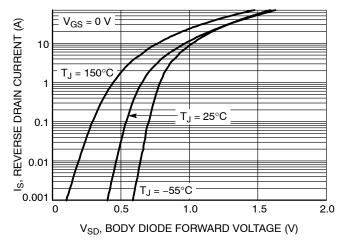


Figure 5. Body Diode Forward Voltage Variation vs. Source Current and Temperature

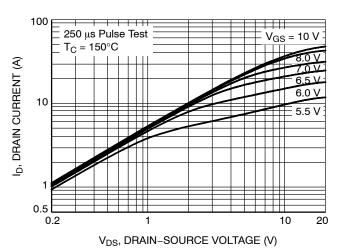


Figure 2. On–Region Characteristics 150°C

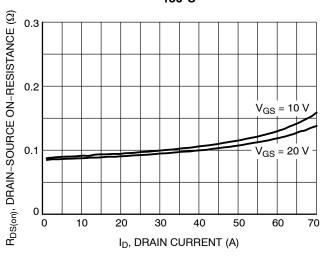


Figure 4. On-Resistance Variation vs. Drain Current and Gate Voltage

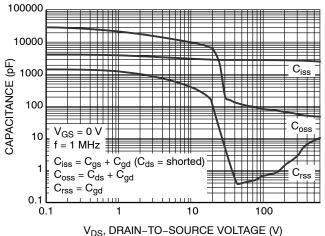
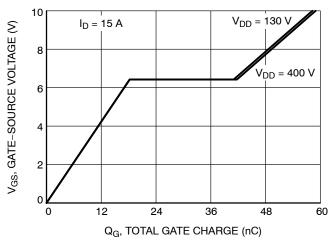


Figure 6. Capacitance Characteristics

# **TYPICAL CHARACTERISTICS**

1.2

 $V_{GS} = 0 V$ 

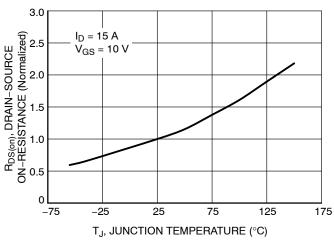


BVDSS, DRAIN-TO-SOURCE BREAKDOWN VOLTAGE (Normalized) I<sub>D</sub> = 10 mA 1.0 8.0 25 -75 -25 75 125 175

Figure 7. Gate Charge Characteristics

Figure 8. Breakdown Voltage Variation vs. Temperature

T<sub>J</sub>, JUNCTION TEMPERATURE (°C)



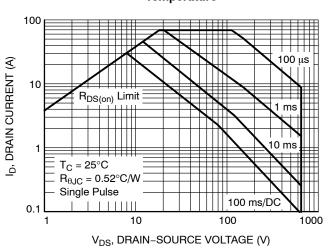
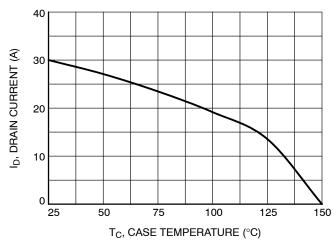


Figure 9. On-Resistance Variation vs. **Temperature** 

Figure 10. Maximum Safe Operating Area



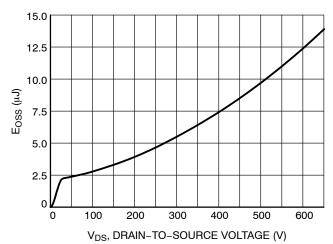
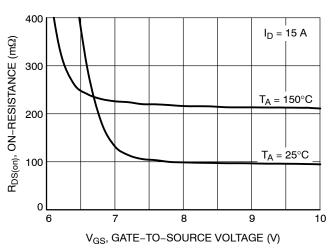


Figure 11. Maximum Drain Current vs. Case **Temperature** 

Figure 12. E<sub>OSS</sub> vs. Drain-to-Source Voltage

# **TYPICAL CHARACTERISTICS**



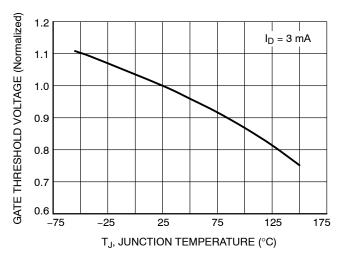


Figure 13. R<sub>DS(on)</sub> vs. Gate Voltage

Figure 14. Normalized Gate Threshold Voltage vs. Temperature

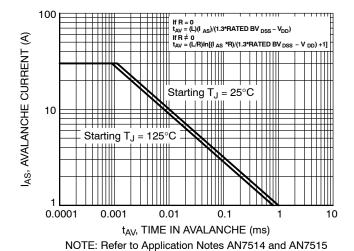


Figure 15. Unclamped Inductive Switching Capability

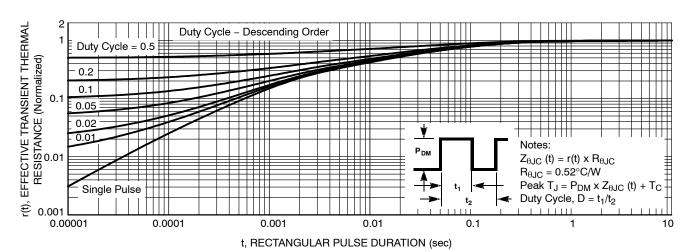


Figure 16. Transient Thermal Response

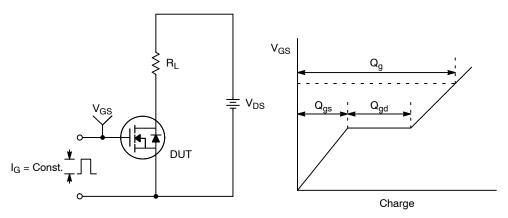


Figure 17. Gate Charge Test Circuit & Waveform

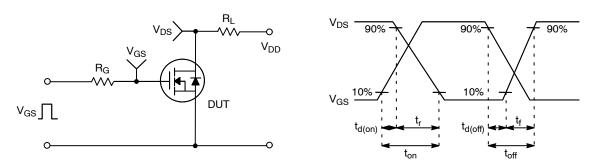


Figure 18. Resistive Switching Test Circuit & Waveforms

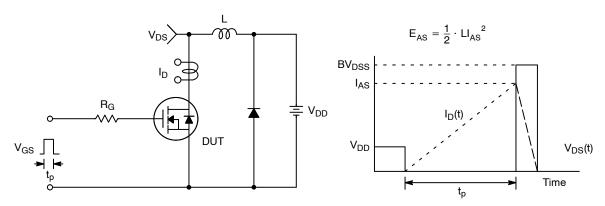


Figure 19. Unclamped Inductive Switching Test Circuit & Waveforms

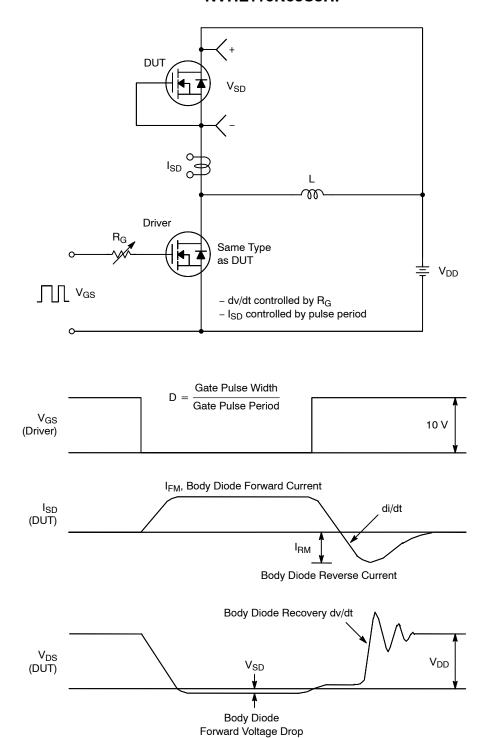
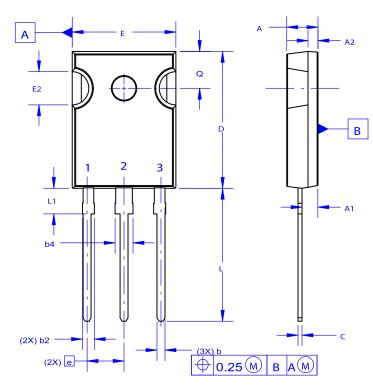


Figure 20. Peak Diode Recovery dv/dt Test Circuit & Waveforms

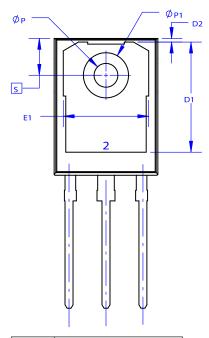
# **PACKAGE DIMENSIONS**

TO-247-3LD CASE 340CX ISSUE A



# NOTES: UNLESS OTHERWISE SPECIFIED.

- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.



DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
D	20.32	20.57	20.82		
Е	15.37	15.62	15.87		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	19.75	20.00	20.25		
L1	3.69	3.81	3.93		
ØР	3.51	3.58	3.65		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D1	13.08	~	1		
D2	0.51	0.93	1.35		
E1	12.81	~	~		
ØP1	6.60	6.80	7.00		

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